

**Please Direct All Correspondence to Customer Number 20995**

---

**TERMINAL DISCLAIMER UNDER 37 CFR § 1.321**

Applicant	:	Hayashi et al.
App. No	:	10/565,696
Filed	:	January 24, 2006
For	:	RESIN FOR RESIST, POSITIVE RESIT COMPOSITION AND METHOD OF FORMING RESIST PATTERN
Examiner	:	Huhn, Richard A.
Art Unit	:	1796

**Mail Stop Amendment**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

***Disclaimer by Assignee***

Assignee, Tokyo Ohka Kogyo Co., Ltd. ("Assignee"), hereby disclaims, except as provided below, the terminal part of any patent granted on the above-referenced application which would extend beyond the earliest expiration date of any patent issuing from U.S. Patent Application No. 10/566,425, and hereby agrees that any patent so granted on the above-identified application shall be enforceable only for and during such period that the above-identified application and U.S. Patent Application No. 11/628,172 are co-owned. This agreement extends to any patent granted on the above-referenced application and shall be binding on its successors or assigns.

Assignee does not disclaim any terminal part of any patent granted on the above-referenced application prior to the earliest expiration date any patent issuing from U.S. Patent Application No. 11/628,172, and that of any patent issuing on the above-identified application in the event that either one later expires for failure to pay a maintenance fee, is held unenforceable, is found invalid, is statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. § 1.321(a), has all claims canceled by a reexamination certificate, or is otherwise terminated prior to expiration of its full statutory term, except for the separation of legal title stated above.